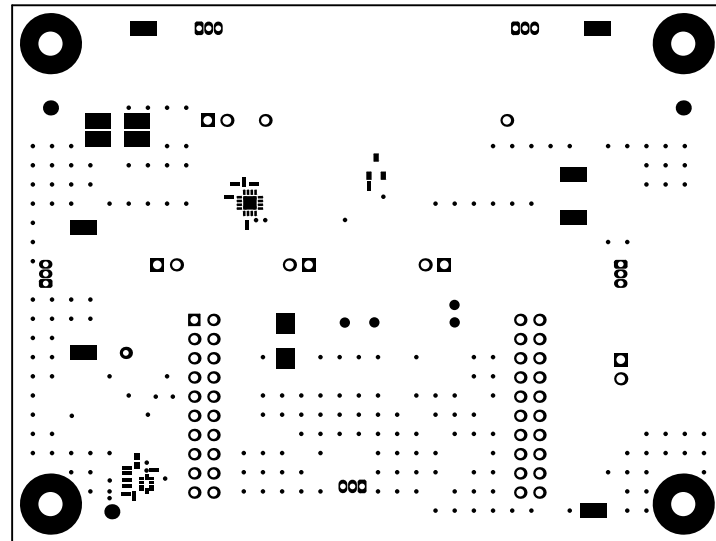


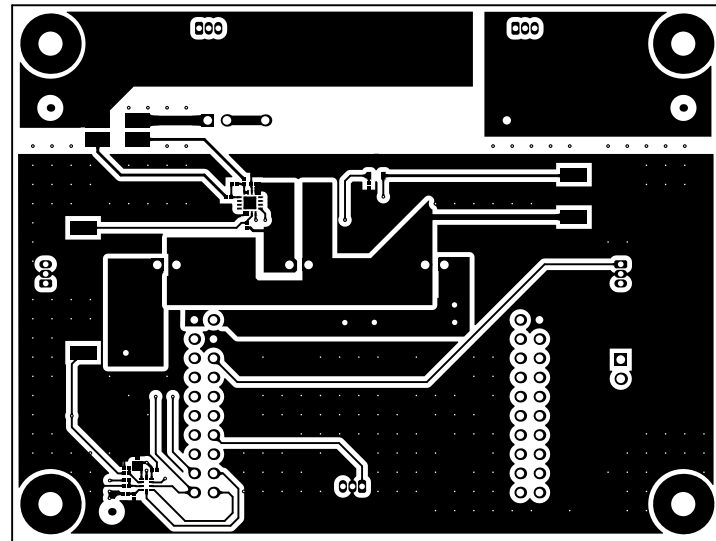
SH-J3

SH-J1 SH-J2 SH-J4

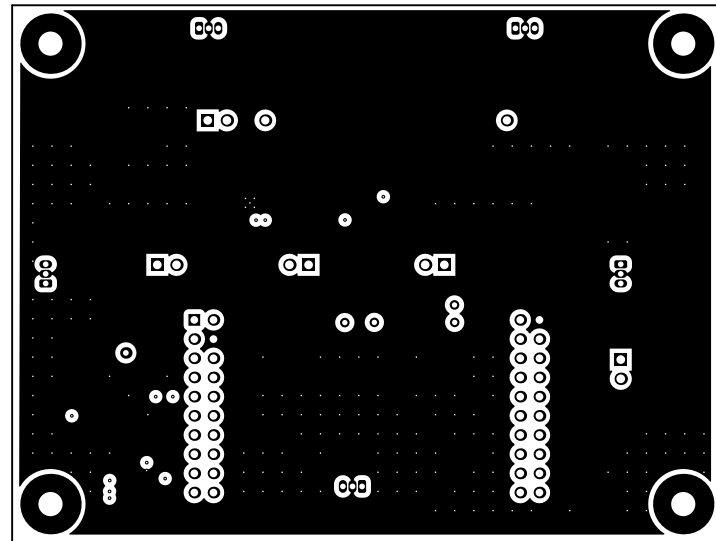
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01596		
PLOT NAME = Top Overlay	GENERATED : 11/16/2017 8:30:24 AM	TEXAS INSTRUMENTS	



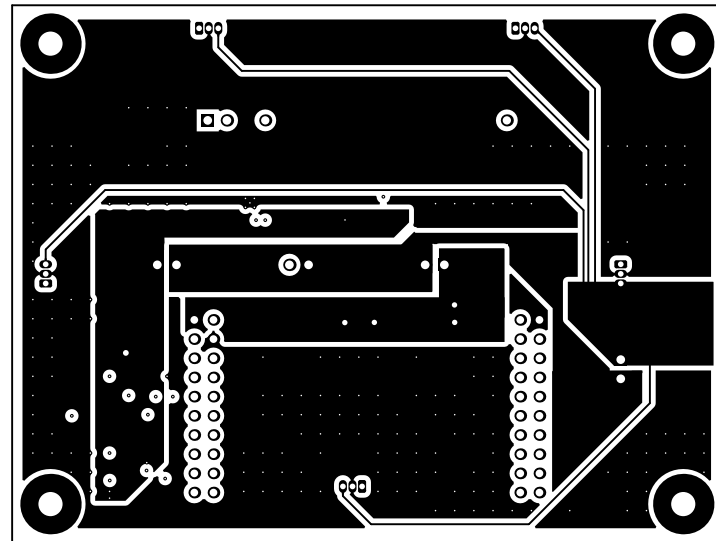
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01596		
PLOT NAME = Top Solder Mask	GENERATED : 11/16/2017 8:30:24 AM	TEXAS INSTRUMENTS	



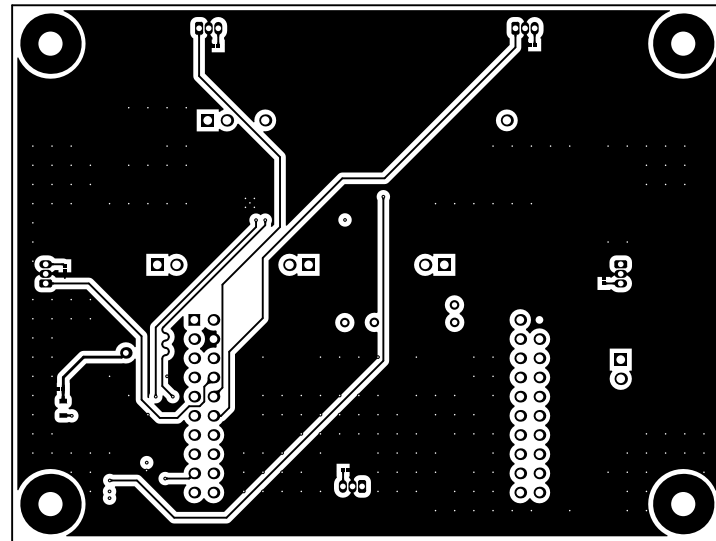
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01596		
PLOT NAME = Top Layer	GENERATED : 11/16/2017 8:30:25 AM	TEXAS INSTRUMENTS	



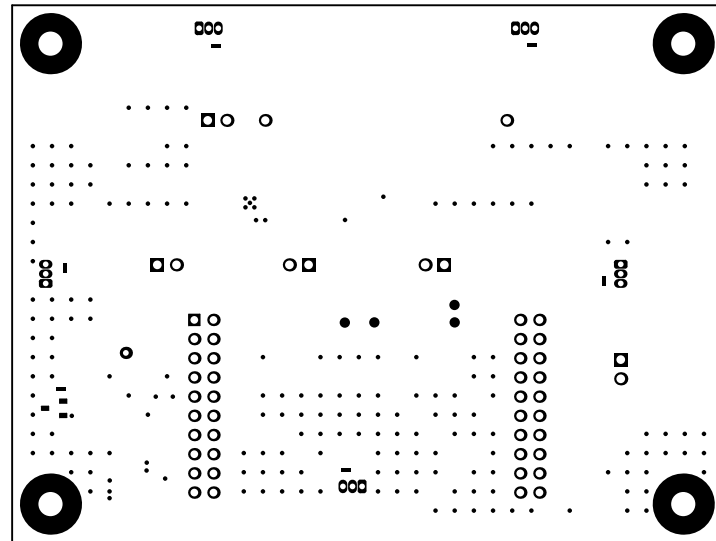
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01596		
PLOT NAME = Signal Layer 1	GENERATED : 11/16/2017 8:30:26 AM	TEXAS INSTRUMENTS	



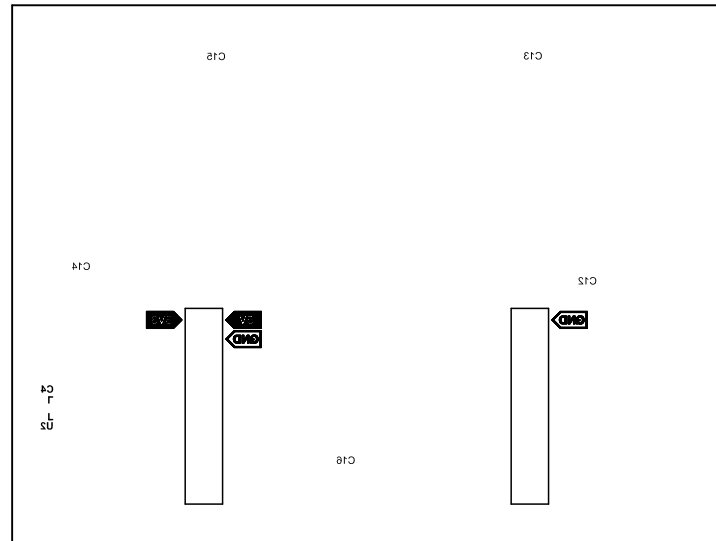
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01596		
PLOT NAME = Signal Layer 2	GENERATED : 11/16/2017 8:30:26 AM	TEXAS INSTRUMENTS	



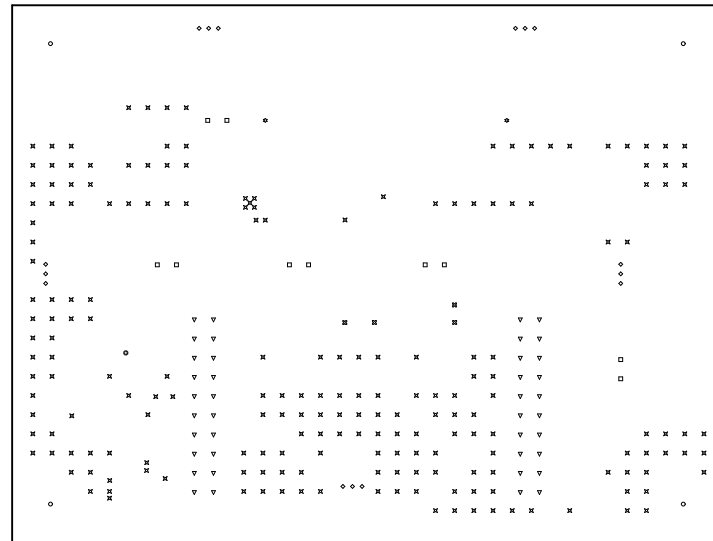
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Plane	TID #: TIDA-01596		
PLOT NAME = Bottom Layer	GENERATED : 11/16/2017 8:30:27 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01596		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/16/2017 8:30:28 AM	TEXAS INSTRUMENTS	

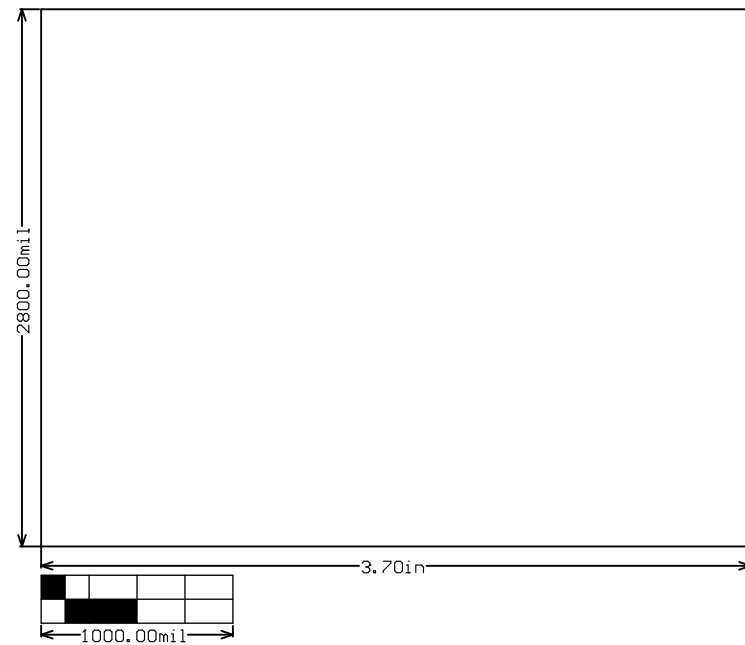


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01596		
PLOT NAME = Bottom Overlay	GENERATED : 11/16/2017 8:30:28 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	200	7.87mil (0.200mm)	PTH	Round	Top Layer - Signal Plane	
⊗	4	28.00mil (0.711mm)	PTH	Round	Top Layer - Signal Plane	
◇	15	29.53mil (0.750mm)	PTH	Round	Top Layer - Signal Plane	
⊙	1	30.00mil (0.762mm)	PTH	Round	Top Layer - Signal Plane	
▽	40	40.16mil (1.020mm)	PTH	Round	Top Layer - Signal Plane	
☆	2	43.31mil (1.100mm)	PTH	Round	Top Layer - Signal Plane	
□	10	45.28mil (1.150mm)	PTH	Round	Top Layer - Signal Plane	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Signal Plane	
276 Total						

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01596		
PLOT NAME = Drill Drawing	GENERATED : 11/16/2017 8:30:29 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01596	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01596		
PLOT NAME = Board Dimensions	GENERATED : 11/16/2017 8:30:30 AM	TEXAS INSTRUMENTS	

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